

承认书

SPECIFICATION FOR APPROVAL

客户 Customer	:	
客户批号 Customer Part No.	:	
型号 Part No.	:	K3535P15KOMZ011
制作人 Prepared By	:	日期 Time: 2020/05/18
审核 Checkedy	:	日期 Time: 2020/05/18
客户回签 Customer Comfirmation	:	日期 Time:

客户意见栏 (Customer' S Proposal)

Approve 承认 (请于认可栏中签名) Disagree 不同意

Reason 原因: _____

版本 (Version): 1.3

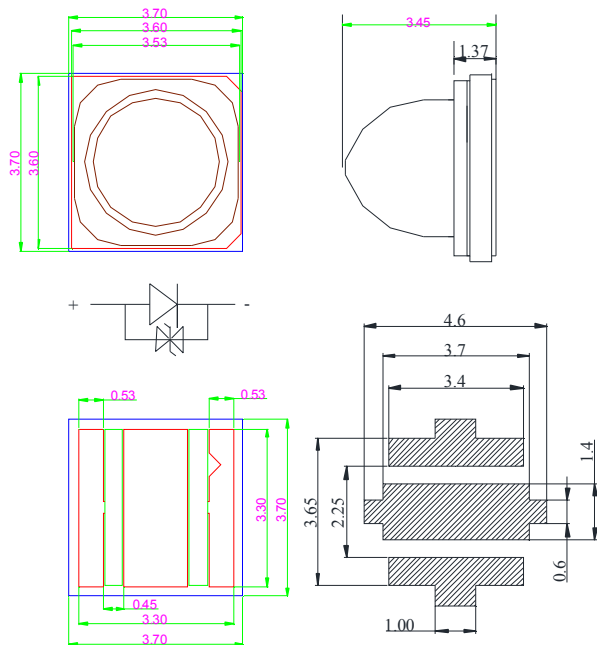
● **Features:**

1. Emitted Color: UV
2. Lens Appearance: Clean quartz lens
3. 3.7x3.7x3.45mm standard package.
4. Suitable for all SMT assembly methods.
5. Compatible with infrared and vapor phase reflow solder process.
6. Compatible with automatic placement equipment.
7. This product doesn't contain restriction Substance, comply ROHS standard.

● **Applications:**

1. UV Curing

● **Package Dimensions:**



NOTES:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.10 mm unless otherwise specified.
3. Specifications are subject to change without notice.

● **Part Numbering System:**

<u>K</u>	<u>3535</u>	<u>P1</u>	<u>5K</u>	<u>0</u>	<u>M</u>	<u>011</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)

- (1) K : Substrate code
- (2) Package type: 3535
- (3) LED Color: P1 means UVA segment
- (4) Chip code
- (5) 0:CRI not required
- (6) M:Type of Silicon
- (7) 011: Code bin



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

● Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Power Dissipation	PD	3	W
DC Forward Current	IF	700	mA
Single Chip Pulsed Forward Current	IFP	1000※	mA
Reverse Voltage	VR	5	V
Operating Temperature	Topr	-30 ~ +80■	°C
Storage Temperature	Tstg	-40 ~ +120	°C
Soldering Temperature	Tsol	260for5sec△	°C

※Duty 1/10, Pulse Width 0.1ms.

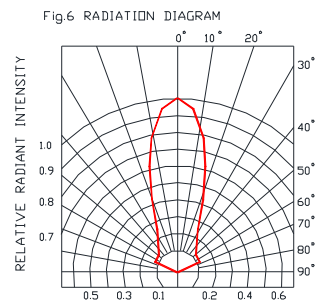
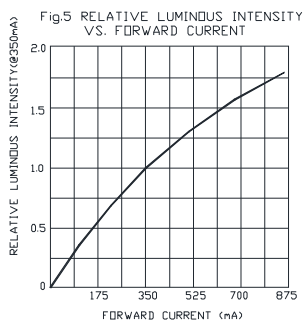
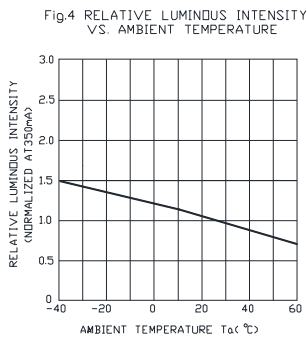
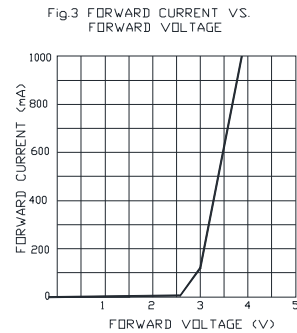
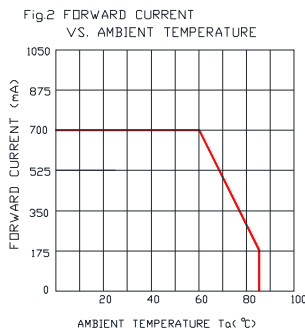
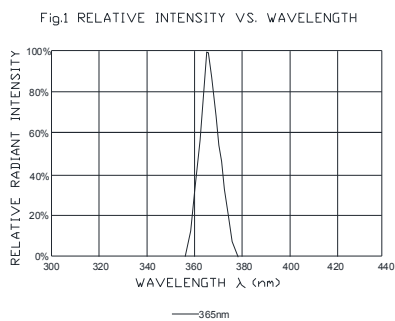
△Soldering time max 10sec

■please refer to IF-Ta diagram of curves for the temperature during application

● Parameter

Parameter	Symbol	Value			Unit	Test condition
		Min.	Typ.	Max		
Forward Voltage	Vf	-	3.7	-	V	If=700mA
Reverse Current	Ir	-	-	10	μ A	VR=5V
Viewing angle	2θ1/2	-	30	-	Deg	If=700mA
Peak Wavelength	λp	365	-	370	nm	If=700mA
Luminous Power	Po		900	-	mw	If=700mA

● Typical Electro-Optical Characteristics Curves



● **Test items and results of reliability**

Type	Test Item	Test Conditions	Note	Number of Damaged
Operation Sequence	Life Test	$T_a=25^{\circ}\text{C}$ $I_F=700\text{mA}$	1000 hrs	0/22
	High Humidity Heat Life Test	85°C RH=85% $I_F=700\text{mA}$	500 hrs	0/22
Environmental Sequence	Temperature Cycle	-45°C 30min $-\uparrow\downarrow 20$ min 105°C 30min	100 cycle	0/22
	Thermal Shock	-10°C 15min $-\uparrow\downarrow 5$ sec 100°C 15min	100 cycle	0/22
	High Humidity Heat Cycle	$30^{\circ}\text{C} \leftrightarrow 65^{\circ}\text{C}$ 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	$T_a=100^{\circ}\text{C}$	1000 hrs	0/22
	Humidity Heat Storage	$T_a=85^{\circ}\text{C}$ RH=85%	1000 hrs	0/22
	Low Temperature Storage	$T_a=-40^{\circ}\text{C}$	1000 hrs	0/22

● **Judgment criteria of failure for the reliability**

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	V_F (V)	$I_F=700\text{mA}$	Over $U^1 \times 1.2$
Reverse current	I_R (uA)	$V_R=5\text{V}$	Over $U^1 \times 2$
Luminous intensity	I_v (mcd)	$I_F=700\text{mA}$	Below $S^1 \times 0.5$

Note: 1. U means the upper limit of specified characteristics. S means initial value.

2. After each test, remove test pieces, wait for 2 hours and test pieces have returned to ambient temperature, then take next measurement.

● **Soldering :**

1. Manual Soldering

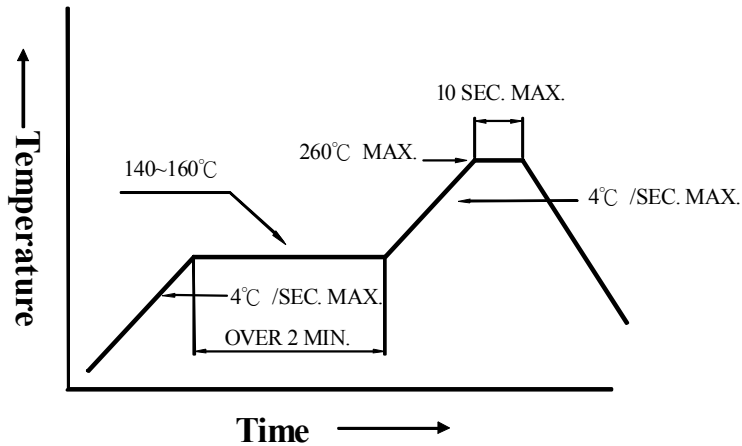
The temperature of the iron tip should not be higher than 350°C and Soldering time to be within 3 seconds per solder-pad.

2. Reflow Soldering

Preheating : 140°C~160°C±5°C, within 2 minutes.

Operation heating : 260°C (Max.) within 10 seconds. (Max)

Gradual Cooling (Avoid quenching).



● Storage:

In order to avoid the absorption of moisture, it is recommended to solder LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C (41°F) Humidity : RH 60 % Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
 - a. Completed within 168 hours.
 - b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:
 - (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions:
48 hours at 60°C±3°C.

● Package and Label of Products:

- (1) Package: Products are packed in one bag of 500 pcs (one taping reel) and a label is attached to each bag.
- (2) Label:

Part No. : XXXXXXXXXXXX
Type No. : E-XXXX-XX-XX-XX-XXX
VF(700mA) : XX-XX
IV(700mA) : XXXX-XXXX
CCT(700mA): XXXX-XXXX
Q'TY : XXXXPCS
Lot No. : X-XXX-XX-X

● Tapping and packaging specifications (Units: mm)

